Design Issues for a 50W VHF/ UHF Solid State RF Power Amplifier

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thanks WWROF (wwrof.org)

Who Is K9LA?

- First licensed in October 1961 as WN9AVT
 - Selected K9LA in 1977
- Enjoy propagation, DX, contests, antennas, vintage rigs
- RF design engineer by profession (mostly RF power amplifiers)
 BSEE 1969 and MSEE 1972 from Purdue University
 - Motorola Land Mobile 1974 to 1988 (Schaumburg and Fort Worth)
 - FM Power Amplifiers from 30 MHz to 512 MHz at 30 W to 100 W
 - Patent US4251784 Apparatus for Parallel Combining An Odd Number of Semiconductor Devices
 - Raytheon (formerly Magnavox) 1988 to Oct 2013 (Fort Wayne)
 - Power Amplifiers from 30 MHz to 2 GHz and from 10 W to 1 KW
 - Constant envelope waveforms (for example, FM) and non-constant envelope waveforms (for example, OFDM)
 - Patent 20040100341 MEMS-Tuned High-Power High-Efficiency Wide-Bandwidth Power Amplifier

Introduction

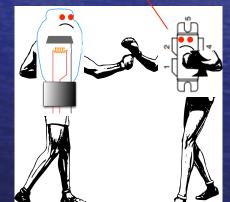
A linear RF power amplifier (PA) takes a little signal and makes it bigger without losing fidelity theoretically!

This presentation discusses several design issues for a very broadband 50 Watt power amplifier
This presentation is not a construction project
This presentation does not discuss all the issues tied to RF power amplifier design

There are books that do this
Cripps, Kenington, Dye & Granberg, etc

My Work With Transistors

- 1974-1988: BJTs (bipolar junction transistors)
 My early days at Motorola wow, 6 dB gain at 450 MHz!
- Igen at a so much a so
- 2000-2010: Lateral MOS (LDMOS)
 - More gain than Vertical MOS, better thermal interface
 - About \$1/watt when I retired in October 2013
- 2010-2013: GaN (gallium nitride)
 - Less dispersion of output parameters vs freq
 - Easier to match over wide range of frequencies
 - Depletion mode need negative gate voltage
 - Voltage sequencing required
 - About \$4/watt when I retired in October 2013
- Summary for my designs
 - LDMOS in PAs below 1 GHz and narrow band PAs up to 2 GHz
 - GaN for wideband PAs from 30 MHz to 2 GHz



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settle this once and for all!

Broadband Design

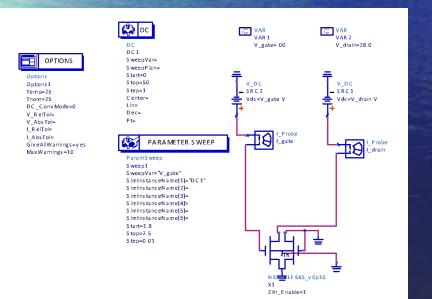
- Let's look at a 50 W PA from low VHF thru high UHF for a multitude of waveforms
 - 50 W means 50 W PEP (Peak Envelope Power) capability
 - 50 W continuous (slow CW) if heat sink and power supply are adequate
 - 50 W PEP for SSB
 - 12.5 W carrier for AM (AM peak-to-carrier ratio = 6 dB)
- Use a BLF645 push-pull LDMOS transistor
 - From NXP (formerly Philips)
- Suitable for 6m, 2m, 1.25m, 70cm and 33cm amateur bands (50 – 928 MHz)

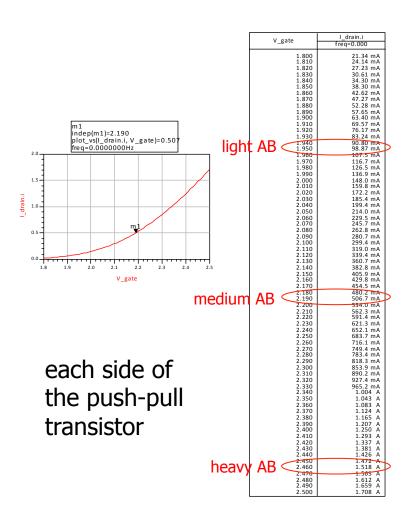
Design Decisions

Ida Class AB for decent linearity (for non-constant) envelope waveforms) with reasonable efficiency - How far into Class AB? Other classes (A, B, C, D, E, F, F⁻¹, S, etc) – not addressed Drain-to-gate feedback Reduce gain at low-frequencies for improved stability Reduce dispersion of Z_{in} Flatten gain across operating bandwidth Desired load impedance To meet output power, efficiency and linearity goals

Idq from ADS

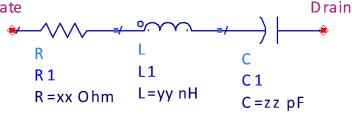
 Use Agilent's ADS (Advanced Design System) to simulate Id vs Vg





Feedback

- I' ve always believed it's a good idea to use some feedback to improve low frequency stability
- I usually used drain-to-gate feedback

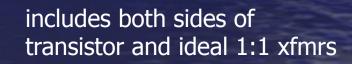


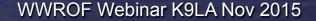
L1 is usually parasitic inductance from layout and parts themselves

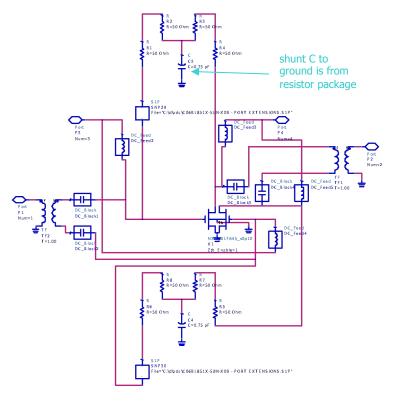
 Sometimes need additional series R at gate or shunt R at gate for stability

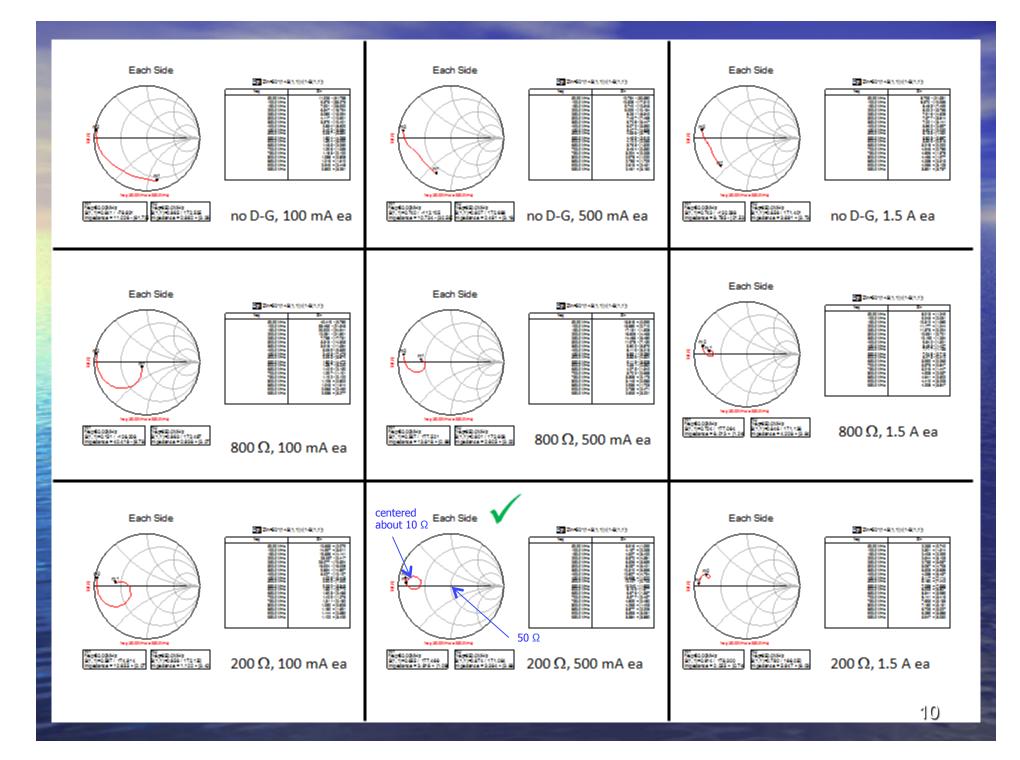
Input Impedance from ADS

- Going to be low
- Idq and feedback play important role
- Would like small dispersion of input impedance vs frequency
 - tight impedance arc
- Look at combinations of
 - Feedback R
 - none (infinite Ω), 800 Ω, 200
 Ω
 - Idq (each side)
 - light AB (100 mA), medium AB (500 mA), heavy AB (1.5 A)









Caveat on Input Impedances

- They are s-parameters
 - Gates driven with small signal
- BLF645 load impedance set to 50 Ω each side
 - -100Ω drain-to-drain
 - Actual desired load ~ $V^2/(2 \times Pout) = 13 \Omega$ each side = 26 Ω drain-to-drain (at low frequencies)
- Output load impedance affects input impedance

 When bias BLF645 to ~ 3 A drain current (emulating large signal) and terminate BLF645 with 26 Ω drain-todrain, 'large signal' input impedances are very similar to 'small signal' input impedances

– Sometimes two "wrongs" make a "right" !

Input Network Design

 For 200 Ω feedback and 500 mA Idq each side

Z_{in} vs Frequency centered around 10 Ω
4:1 transformer is a good starting point
Don't put right at the body of the transistor
Use a little bit of series L (in conjunction with shunt C) to step up the BLF645 input impedance at the higher frequencies

– BLF645 Z_{in} decreases with increasing frequency

Output Network Design

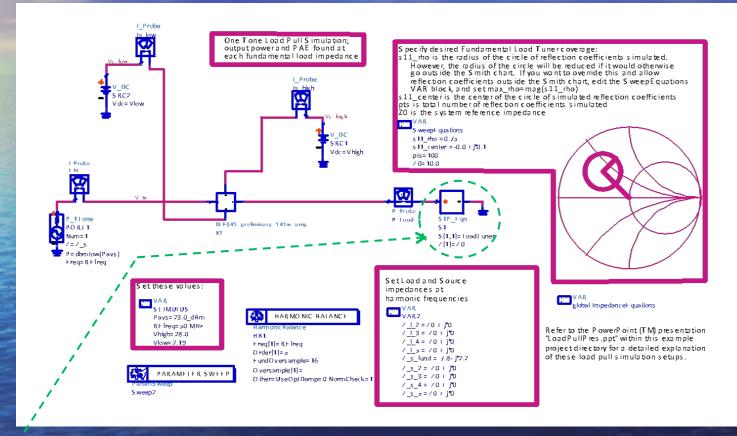
- What load impedance does the BLF645 want to see to meet output power, efficiency and linearity goals?
- Do load-pull in ADS with 200 Ω feedback and Idq = 500 mA (each side)

Definitions

- Pdel is power delivered to load (in dBm)
- PAE is power added efficiency (in %)
 - $PAE = Pdel Pin \times 100$

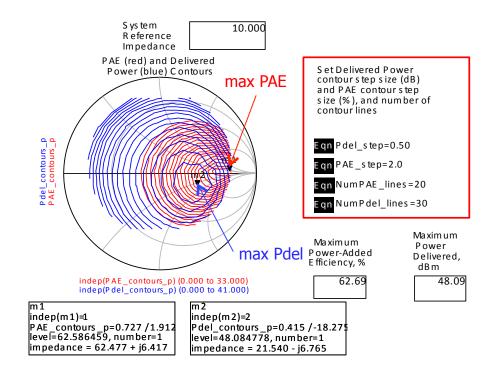
Vd x Id

ADS Load-Pull



LoadTuner varies impedances over desired range while recording Pdel and PAE

PAE/Pdel Data



- Frequency is 50 MHz
- Pin = +23 dBm
- Z_o of Smith chart is 10 Ω
- Max Pdel is +48.09 dBm
- Max PAE is 62.69%
- Max Pdel and PAE usually don't occur at the same load impedance
- Decision design for max Pdel

- $Z_{\text{desired load}} = 21.5 - j 6.8 \Omega$

- PAE at max Pdel ~ 50%
- Pdel at max PAE ~ 45 dBm

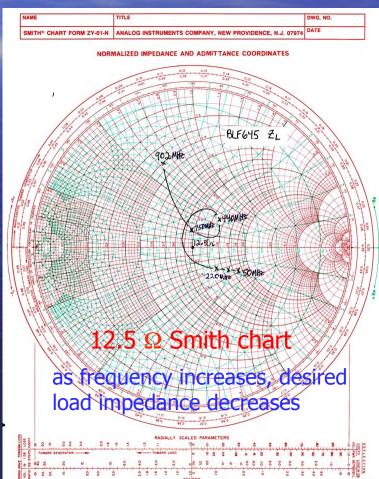
Desired Z_{load} vs Frequency

Do load-pull at other frequencies

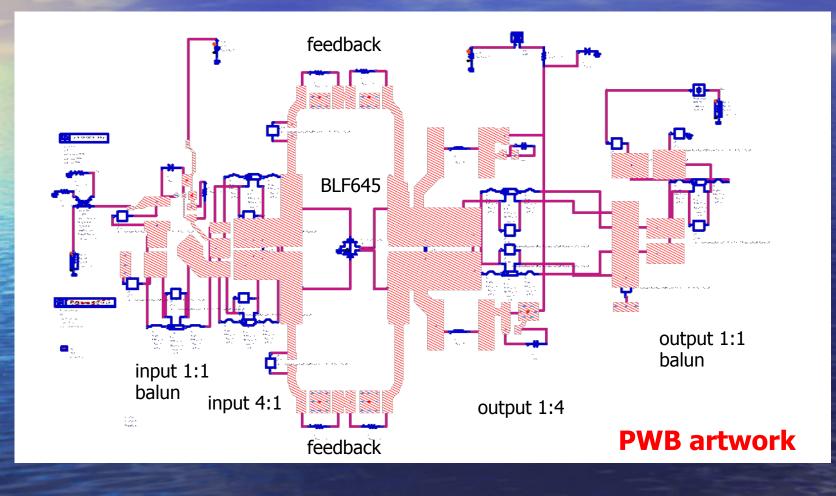
- 50 MHz 21.5 j 6.8 Ω
- 145 MHz 19.2 j 5.6 Ω
- 220 MHz 16.8 j 4.4 Ω
- 440 MHz 16.5 + j 6.0 Ω
- 750 MHz 11.8 + j 3.2 Ω
- 902 MHz 5.0 + j 8.0 Ω

All impedances are drain-to-drain

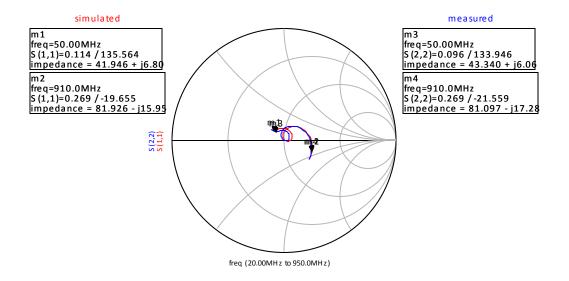
- Plotted on 12.5 Ω Smith chart
- Desired load mostly around 12.5 Ω
 - Suggests 4:1 xfmr
- Using simple formula, we estimated
 26 Ω at low frequencies
 - That's about where 50 MHz is



ADS Model: PWB and Schematic



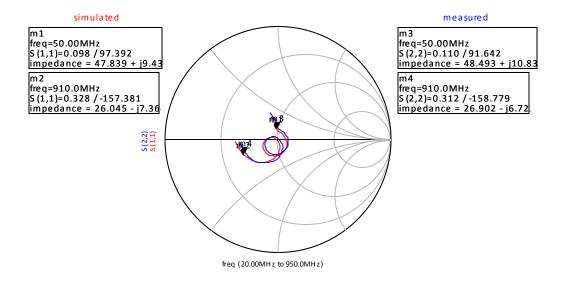
PWB + Schematic: Input



Looking into input RF connector with 12.4Ω gate-to-gate chip resistor substituted for BLF645

excellent correlation

PWB + Schematic: Output

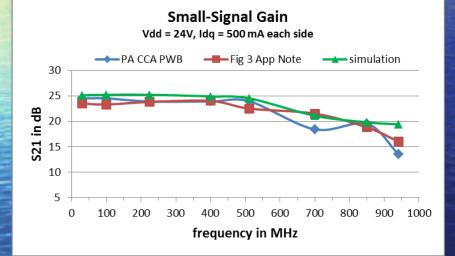


Looking into output RF connector with 12.4Ω drain-to-drain chip resistor substituted for BLF645

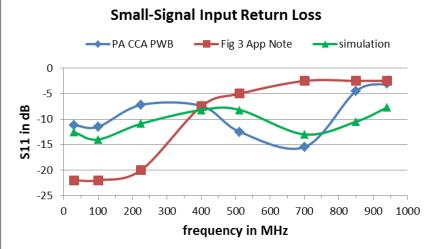
excellent correlation

Small-Signal Comparison Simulated vs Measured

S21



S11



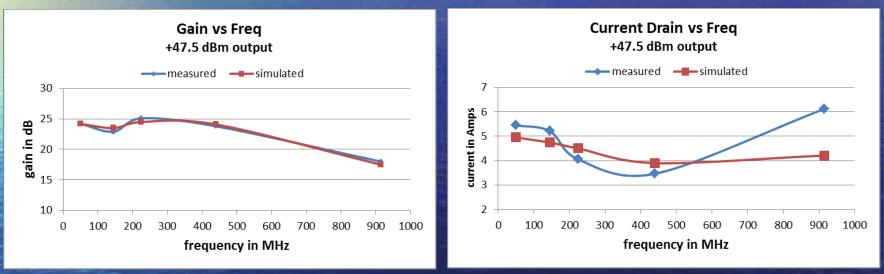
good correlation overall

'PA CCA PWB' is measured breadboard 'Fig 3 App Note' is data from NXP app note 'Simulation' is from ADS model

decent correlation between 'PA CCA PWB' and 'Simulation'

Large-Signal Comparison Simulated vs Measured

at 28V



excellent correlation

decent correlation

'Measured' is the breadboard 'Simulation' is from ADS model

Large-Signal Performance Measured Data

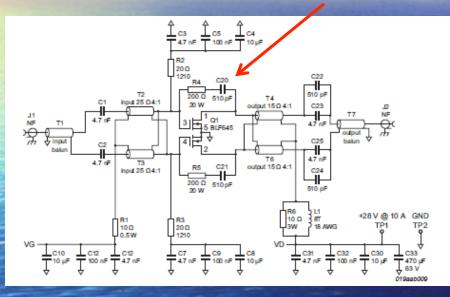
at 281/

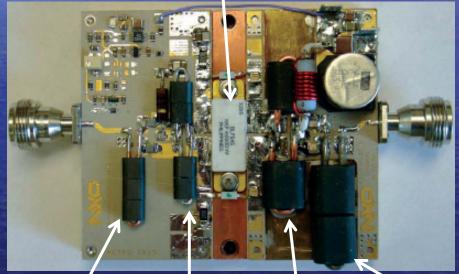
al ZOV									
	<u>freq</u>	Pout	<u>Pin</u>	<u>Gain</u>	<u>Current</u>	<u>Eff</u>	<u>2f</u>	<u>3f</u>	<u>Input RL</u>
	50 MHz	47.5 dBm	23.3 dBm	24.2 dB	5.45 A	36.8 %	-43 dBc	-13 dBc	12.2 dB
H. LAN	145	47.5	24.6	22.9	5.21	38.5	-64	-14	7.5
1.11	225	47.5	22.4	25.1	4.05	49.6	-36	-17	9.0
	440	47.5	23.7	23.8	3.46	58.0	-54	-26	8.2
	915	47.5	29.5	18.0	6.12	32.8	-38	-45	14.4

this is the breadboard

BLF645 Design Implementation

drain-to-gate feedback (2 pl)





BLF645

input 1:1 input 4:1 output 1:4 output 1:1 balun balun

schematic and breadboard photo from NXP App Note AN10953

Caveat On Simulation

 Simulation results are only as good as the models used Chip capacitor example – 300 pF ATC 100B (100 mil cube)

Very simple model – series C

Better model – series RLC

R=0.1 Ω, L=0.5 nH

Best model – from network analyzer measurement of cap



Other Components, and IMD

SRL

SRL1

R=12.4 Ohm

L=1.07 nH

0805 chip resistor

X₁ about 6 ohms at 900 MHz

Resistors

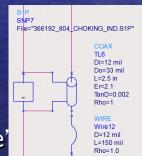
- Series R-L is usually sufficient
- Generally not in the RF path
- Inductors
 - Might be some inter-winding capacitance at the higher frequencies

RF transformers

- Used transmission-line transformers (TLT)
- Modeled with a length of coax
- Impact of ferrite modeled as inductance of outer conductor
 - S-parameter measurement we called it 'magnetizing inductance'

Simulating IMD

- Areas of concern: transistor model, impact of ferrite on xfmrs
- Use results cautiously rule of thumb for medium Class AB if PEP of waveform is at P1dB, 2-tone IMD \sim -25 dBc or AM distortion \sim 5%

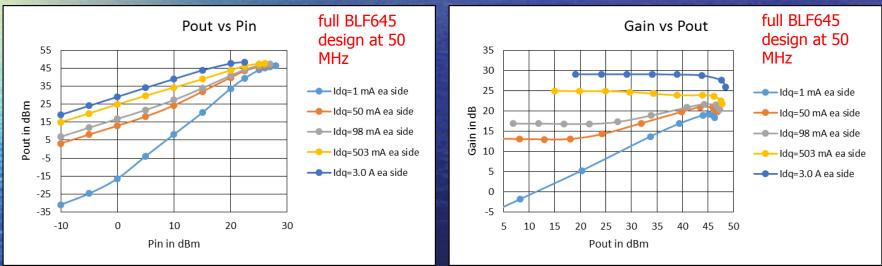




More Simulation Comments What if you don't have simulation capabilities? Design the old-fashioned way Start with data sheet impedances Play around on the bench a lot – as Ed Paragi WB9RMA and I did in our early PA design days Simulation allows you to look at many "what if" scenarios in a short amount of time The model can be used for trends, and if it's good enough it can be used for absolute results (usually the model of the transistor is the limiting factor)

Simple Characterization of a PA

- The November 2015 QST had a Product Review of a 6m amplifier showed a plot of Pout vs Pin
- Better way to characterize a PA plot Gain vs Pout



Gain vs Pout tells class of operation (flat gain is A or medium/high AB), tells gain (from plot), shows compression, and indicates efficiency (A is least efficient)
 Gain vs Pout indicates linearity (flat gain best, gain expansion not good)

Summary

- Discussed design issues for a broadband VHF/UHF PA
- More work needed for <u>complete</u> design
 - P_{in} from 0.2 1.0 W: could add gain compensation
 - Power supply: 28 V at 7 A
 - Heat sink: max dissipation = 120 W need to get the heat out!
 - 5 harmonic filters: push-pull eases 2f rejection (see slide 22)
 - T/R Switch: relays easiest, could use PIN diodes
 - Directional coupler on output: P_{fwd} and P_{refl} , use P_{fwd} for ALC
- Harmonic filters, T/R Sw and dir cplr add loss
- Simulation is a big help, but bench performance determines success or failure
 - Accurate models give accurate simulations
- Thanks to WB9RMA and KB9TAF for comments to these slides